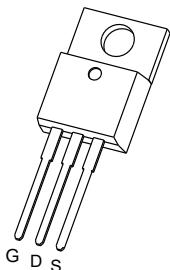


N-Channel 100V(D-S) MOSFET

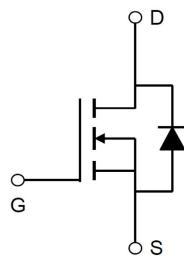
Product summary		
V_{DS}	100	V
$R_{DS(ON)}$ (at $V_{GS}=10V$) Typ.	4.4	$m\Omega$
$I_D(T_c=25^\circ C)$	128	A

Features
<ul style="list-style-type: none"> Low Gate Charge High Current Capability
Applications
<ul style="list-style-type: none"> Current Switching Motor Driving Power management

Pin Configuration



TO-220



Packing Information

Device	Package	Packaging	Quantity
ECFB128N10A	TO-220	Tube	50pcs

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ^A	$T_c=25^\circ C$	A
		$T_c=100^\circ C$	A
I_{DM}	Pulse Drain Current Tested ^B	417	A
I_{AS}	Avalanche Current ^C	42	A
E_{AS}	Single Pulse Avalanche Energy ^C	265	mJ
P_D	Power Dissipation ^D $T_c=25^\circ C$	167	W
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
R_{eJC}	Thermal Resistance-Junction to case	0.75	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	2.7	4.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^E	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	--	4.4	5.3	$\text{m}\Omega$
V_{SD}	Diode Forward Voltage	$I_{\text{S}}=1\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.0	V
I_{S}	Diode Continuous Current	$T_C=25^\circ\text{C}$	--	--	167	A
Dynamic Parameters ^F						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}$ $f=1\text{MHz}$	--	2816	--	pF
C_{oss}	Output Capacitance		--	614	--	pF
C_{rss}	Reverse Transfer Capacitance		--	7.4	--	pF
R_g	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}$ $f=1\text{MHz}$	--	2.4	--	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V}$	--	42	--	nC
Q_{gs}	Gate-Source Charge		--	9.7	--	nC
Q_{gd}	Gate-Drain Charge		--	10.6	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=50\text{V}, R_L=2.5\Omega$, $R_{\text{GEN}}=6\Omega$, $V_{\text{GS}}=10\text{V}$	--	13	--	ns
t_r	Turn-on Rise Time		--	25	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	43	--	ns
t_f	Turn-off Fall Time		--	37	--	ns
t_{rr}	Reverse recovery time	$I_F=15\text{A}$, $di/dt=100 \text{ A}/\mu\text{s}$	--	60	--	ns
Q_{rr}	Reverse recovery charge		--	61	--	nC

- A. Computed continuous current assumes the condition of T_J_{Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
- B. This single-pulse measurement was taken under $T_J_{\text{Max}} = 150^\circ\text{C}$.
- C. This single-pulse measurement was taken under the following condition [$L = 300\mu\text{H}$, $V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=50\text{V}$] while its value is limited by $T_J_{\text{Max}} = 150^\circ\text{C}$.
- D. The power dissipation PD is based on $T_J_{\text{Max}} = 150^\circ\text{C}$.
- E. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 0.5\%$.
- F. Guaranteed by design, not subject to production testing.

Typical Characteristics

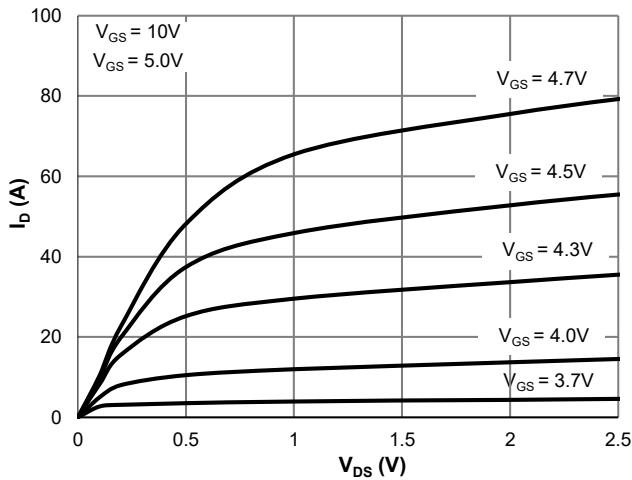


Figure 1: Saturation Characteristics

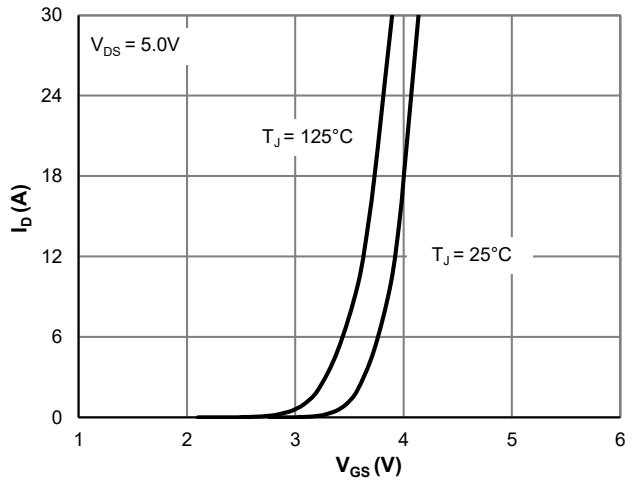


Figure 2: Transfer Characteristics

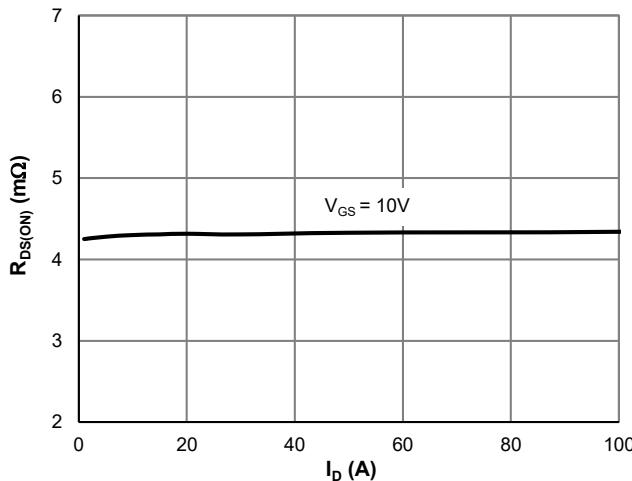


Figure 3: $R_{DS(ON)}$ vs. Drain Current

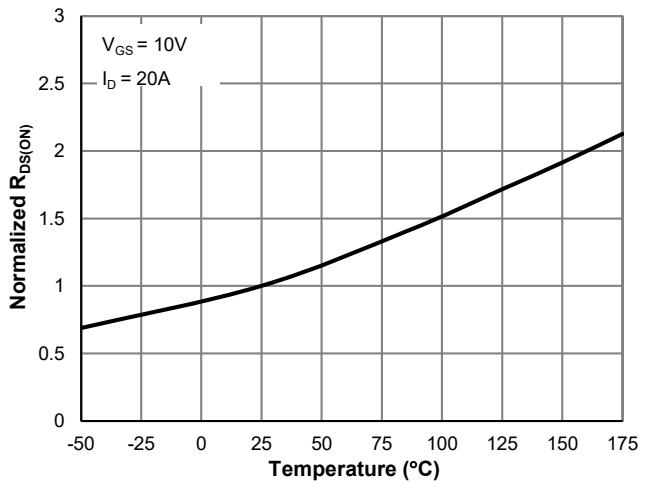


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

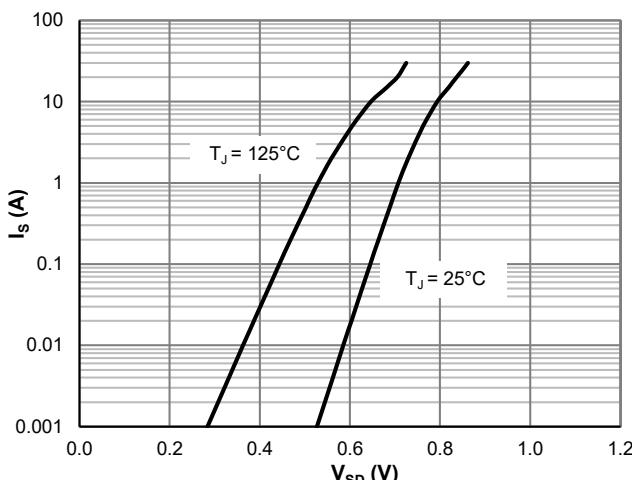


Figure 5: Body-Diode Characteristics

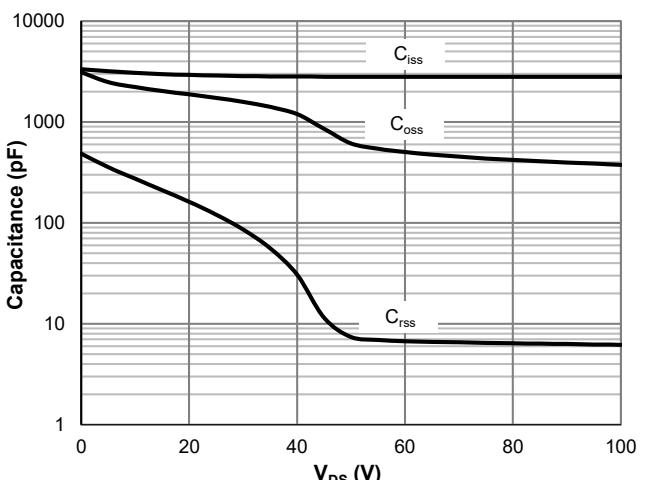


Figure 6: Capacitance Characteristics

Typical Characteristics

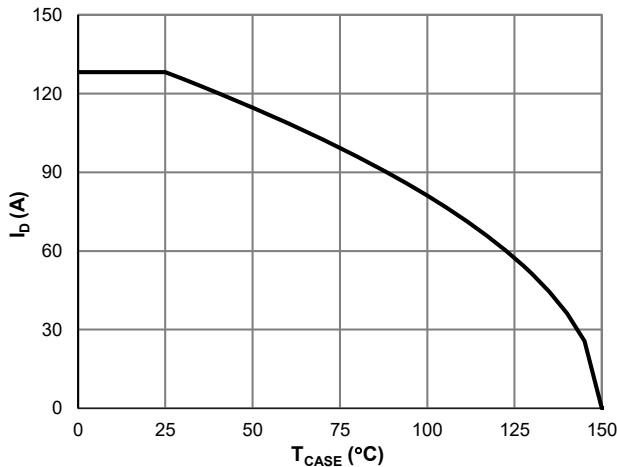


Figure 7: Current De-rating

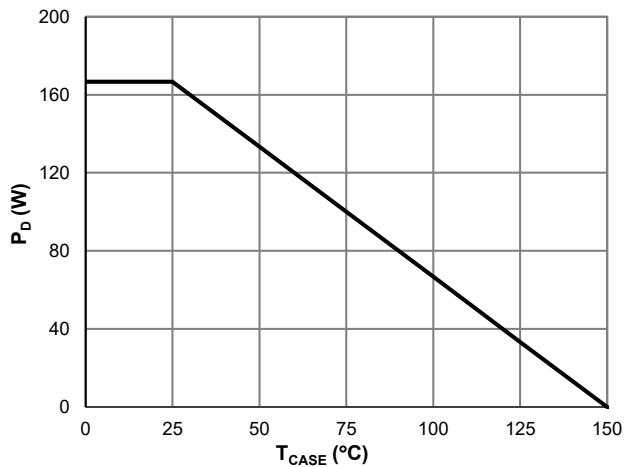


Figure 8: Power De-rating

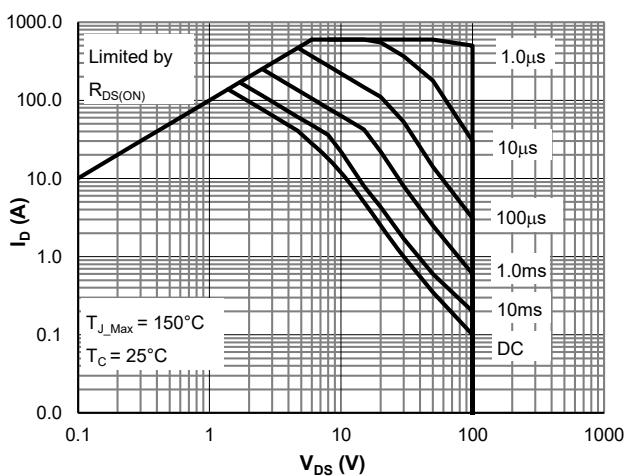


Figure 9: Maximum Safe Operating Area

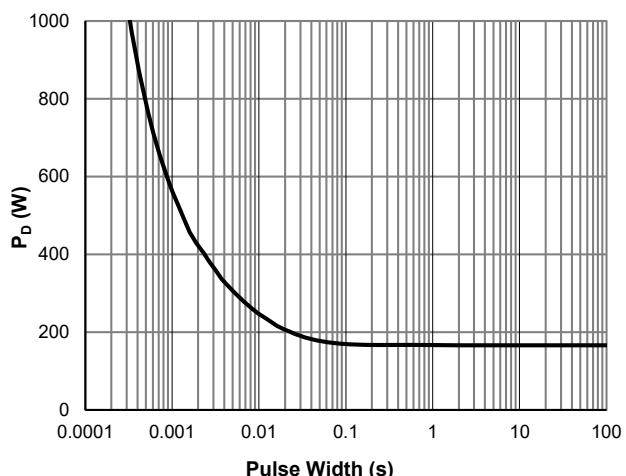


Figure 10: Single Pulse Power Rating, Junction-to-Case

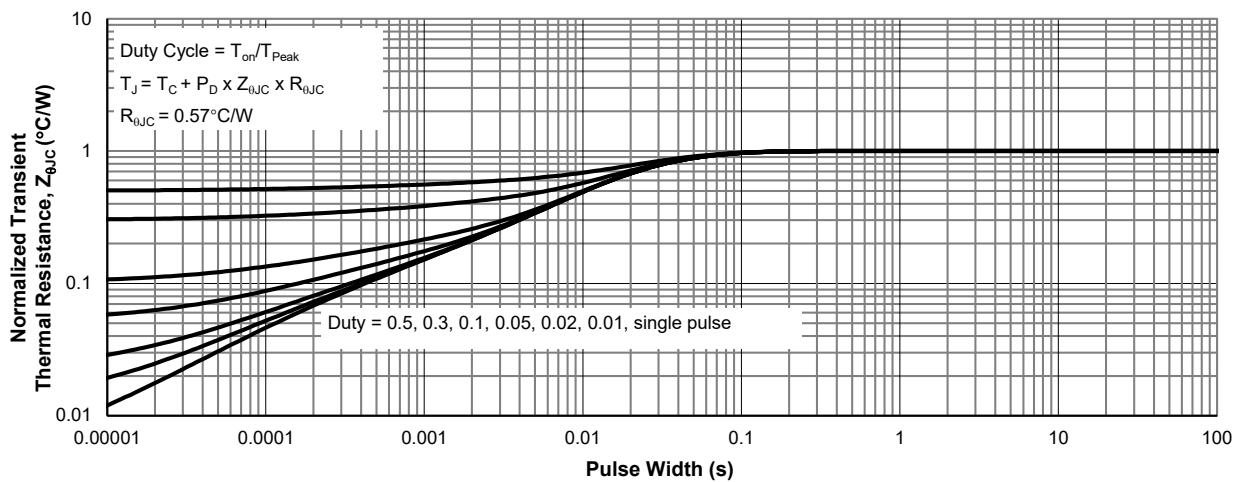
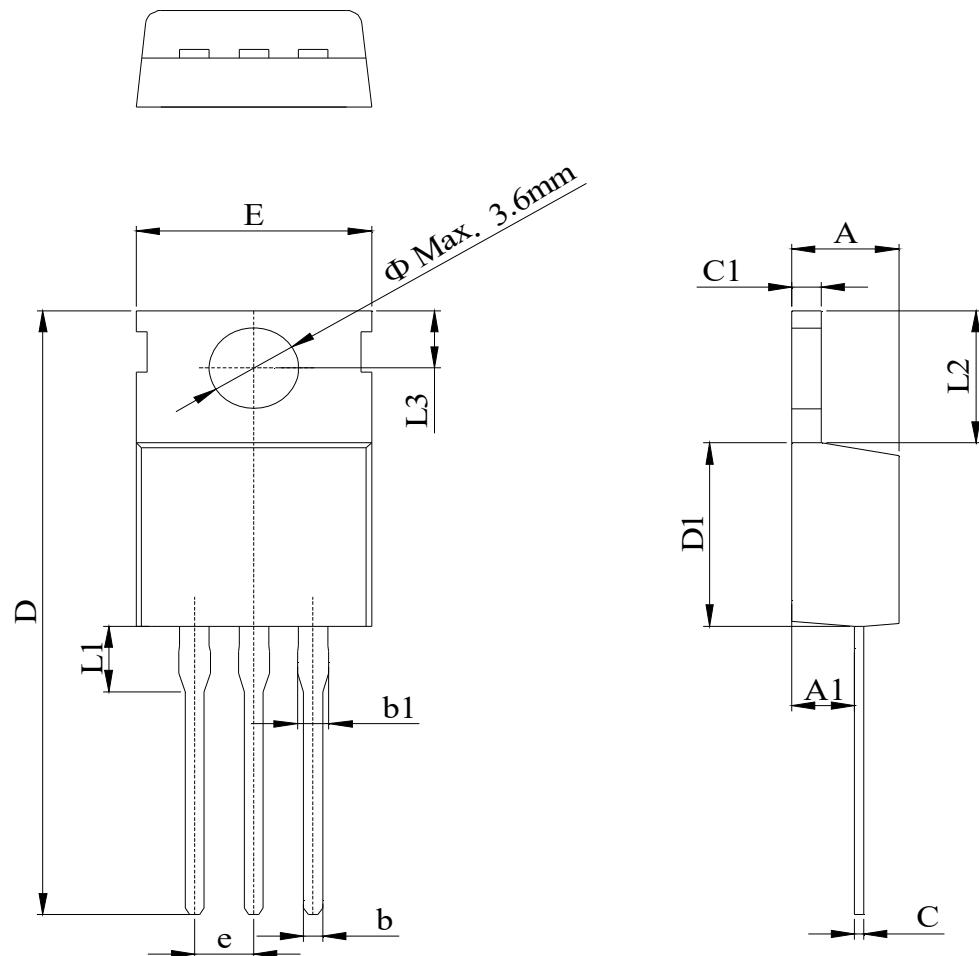


Figure 11: Normalized Maximum Transient Thermal Impedance

TO-220 Package Information


DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.37		4.70
A1	2.20		3.00
b	0.70		0.95
b1	1.14		1.70
C	0.45		0.60
C1	1.23		1.40
D	28.00		29.80
D1	8.80		9.90
E	9.70		10.50
L1			3.80
L2	6.25		6.90
L3	2.40		3.00
e		2.54 BSC	